connectors								
SPECIFICATION								
宏至	女 電	[子股份有限]	良公 司					
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	No.	13, Dongyuan Rd., Jhongli Cit	у,					
	Taoy	uan County 320, Taiwan (R.O.	C.)					
	TEI	: +886-3-463-2808						
	FAX	X: +886-3-463-1800						
SPEC. NO.: PS-52552-XXXXX-XXX REVISION: 1								
PRODUCT NAME: 0.5 mm PITCH ZIF BACK FLIP FPC/FFC CONN.								
	SMT	R/A D/C TYPE						
PRODUCT NO: 52552 SERIES								
PREPARED:		CHECKED:	APPROVED:					
Wang, Kai Hur	ıg	Liu, Yuan Huang	Huang Kuo Hua					
DATE: 2021/06/04		DATE: 2021/06/04	DATE: 2021/06/04					

2010/10/31 TR-FM-73015L



#### TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC/FFC CONN. SMT R/A TYPE

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#### TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC/FFC CONN. SMT R/A TYPE

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# 1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
1	ECN-003909	NEW PROJECT SPEC APD1100255	Wang, Kai Hung	2021.06.04



TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC/FFC CONN. SMT R/A TYPE

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## 2 SCOPE

This specification covers performance, tests and quality requirements for 0.5 mm pitch ZIF back flip FPC/FFC CONN. SMT R/A D/C TYPE.

## **3** APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

## 4 REQUIREMENTS

4.1 Design and Construction

- 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
- 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.

#### 4.2 Materials and Finish

- 4.2.1 Contact: High performance copper alloy (Phosphor Bronze)
  - Finish: (a) Contact Area: Refer to the drawing.
    - (b) Under plate: Refer to the drawing.
    - (c) Solder area: Refer to the drawing.
- 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.3 Actuator: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.4 Fitting Nail: Copper Alloy, Finish: Refer to the drawing.

4.3 Ratings

- 4.3.1 Working voltage less than 36 volts AC (per pin)
- 4.3.2 Voltage: 50 Volts AC (per pin)
- 4.3.3 Current: DC 0.5 Amperes (per pin)
- 4.3.4 Operating Temperature : -40 $^{\circ}$ C to +85 $^{\circ}$ C



#### TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC/FFC CONN. SMT R/A TYPE

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## 5 Performance

## 5.1. Test Requirements and Procedures Summary

**REVISION: 1** 

ltem	Requirement	Standard Visual, dimensional and functional per applicable quality inspection plan.							
Examination of Product	Product shall meet requirements of applicable product drawing and specification.								
ELECTRICAL									
ltem	Requirement	Standard							
Low Level Contact Resistance	60 m Ω Max.(initial)per contact 20 m Ω Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA (EIA-364-23)							
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 100 V DC between adjacent terminals. (EIA-364-21)							
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	250 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)							
Temperature rise	30℃ Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70 METHOD 1,CONDITION 1)							



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	MECHANICAL				
Item	Requirement	Standard The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)			
Durability	10 cycles. Without notches of FPC				
FPC Retention Force	20 gf/per pin Min.(Without Lock) (initial) 20 gf/per pin+200gf Min.(With Lock)(initial)	Apply axial pull out force at the speed rate of $25.4 \pm 3 \text{ mm/minute}$ .			
Terminal / Housing Retention Force	30 gf MIN.	Apply axial pull out force at the speed rate of $25.4 \pm 3$ mm/minute. On the terminal assembled in the housing.			
Fitting Nail / Housing Retention Force	30 gf MIN.	Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute On the fitting nail assembled in th housing.			
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)			
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)			



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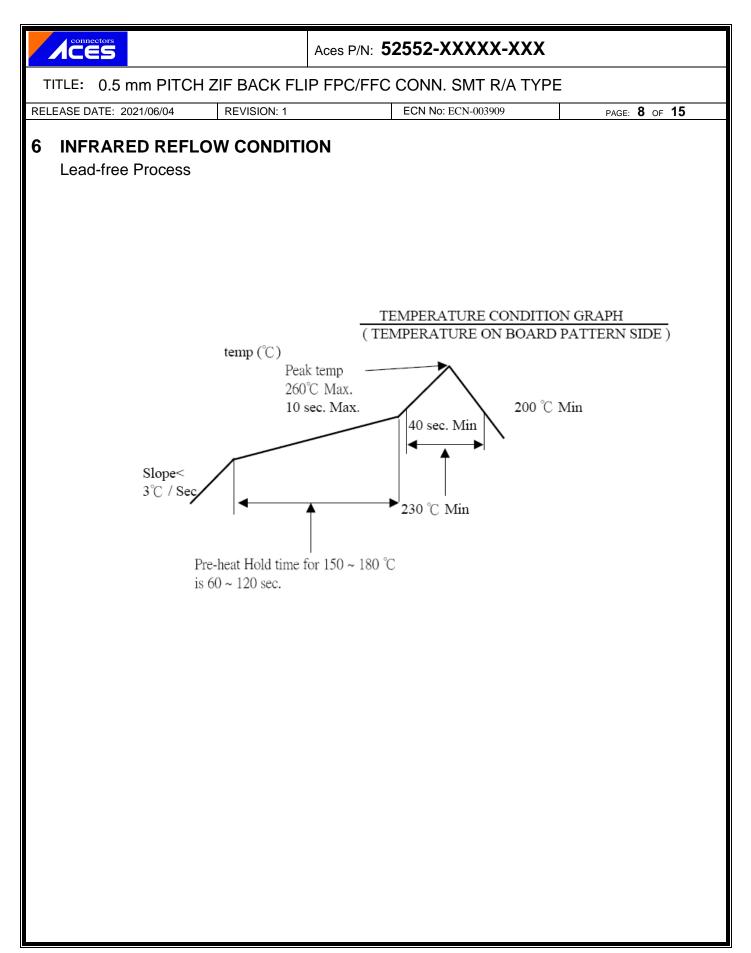
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ENVIRONMENTAL						
ltem	Requirement	<b>Standard</b> Pre Heat : 150°C~180°C, 60~120sec Heat : 230°C Min., 40sec Min. Peak Temp. : 260°CMax, 10sec Max. Cycles : 2				
Resistance to <b>Reflow</b> Soldering Heat	See Product Qualification and Test Sequence Group 10 <b>(Lead Free)</b> No deformation of components affecting performance.					
Hand Soldering Temperature Resistance	Appearance: No damage	T≧ 350°C, 3sec at least				
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +/-3 °C, 30 minutes +85 +/-3 °C, 30 minutes (EIA-364-32, test condition I)				
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector				
Temperature life(heat)	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C±2°C for 96 hours. (EIA-364-17, Test condition A)				
Temperature life(cold)	See Product Qualification and Test Sequence Group 11	Subject mated connectors to t temperature life at -40°C±3°C for 9 hours. (EIA-364-17, Test condition A)				
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, $35^{\circ}$ C (I) Gold flash for 8 hours (II) Gold plating 3u" for 48 hours. (III) Gold plating $\geq 5$ u" for 96 hours. (EIA-364-26)				
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage. shell be conduct by customer request	And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)				

**Note.** Flowing Mixed Gas shell be conduct by customer request.





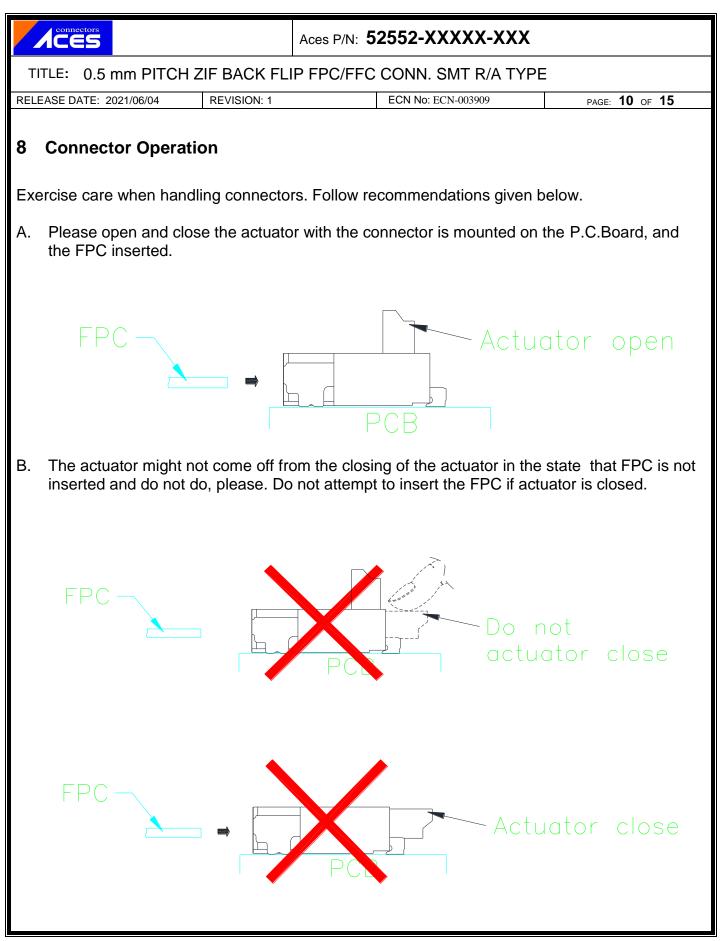
TITLE: 0.5 mm PITCH ZIF BACK FLIP FPC/FFC CONN. SMT R/A TYPE

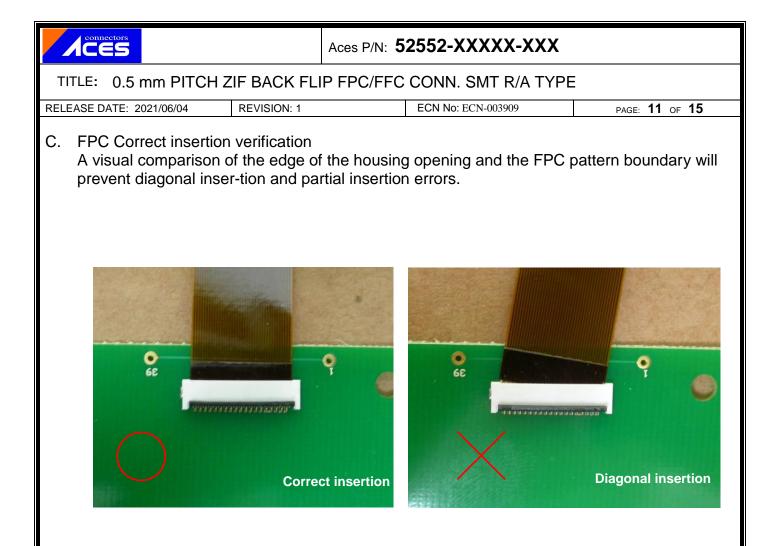
RELEASE DATE: 2021/06/04 REVISION: 1

ECN No: ECN-003909

# 7 PRODUCT QUALIFICATION AND TEST SEQUENCE

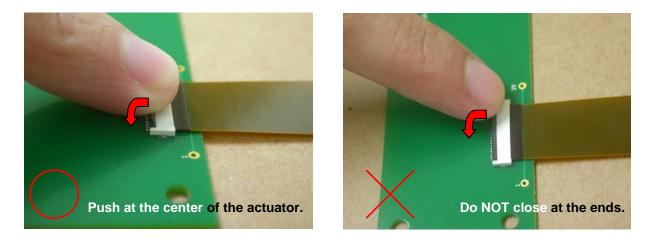
	Test Group										
Test or Examination		2	3	4	5	6	7	8	9	10	11
		Test Sequence									
Examination of Product				1、7	1、6	1、4	1		1	1、3	1、6
Low Level Contact Resistance		1、5	1、4	2、10	2、9	2 \ 5			3		2 \ 9
Insulation Resistance				3、9	3、8						3 • 8
Dielectric Withstanding Voltage				4 • 8	4 • 7						4 • 7
Temperature rise	1										
Durability		3									
Vibration			2								
Shock (Mechanical)			3								
Thermal Shock				5							
Humidity				6							
Temperature life(heat)					5						
Temperature life(Cold)											5
Salt Spray(Only For Gold Plating)						3					
Solder ability							1				
FPC Retention Force		2、4									
Terminal / Housing Retention Force								1			
Fitting Nail /Housing Retention Force								2			
Resistance to Soldering Heat									2		
Hand Soldering Temperature Resistance										2	
Sample Size	2	4	4	4	4	4	2	4	4	4	4



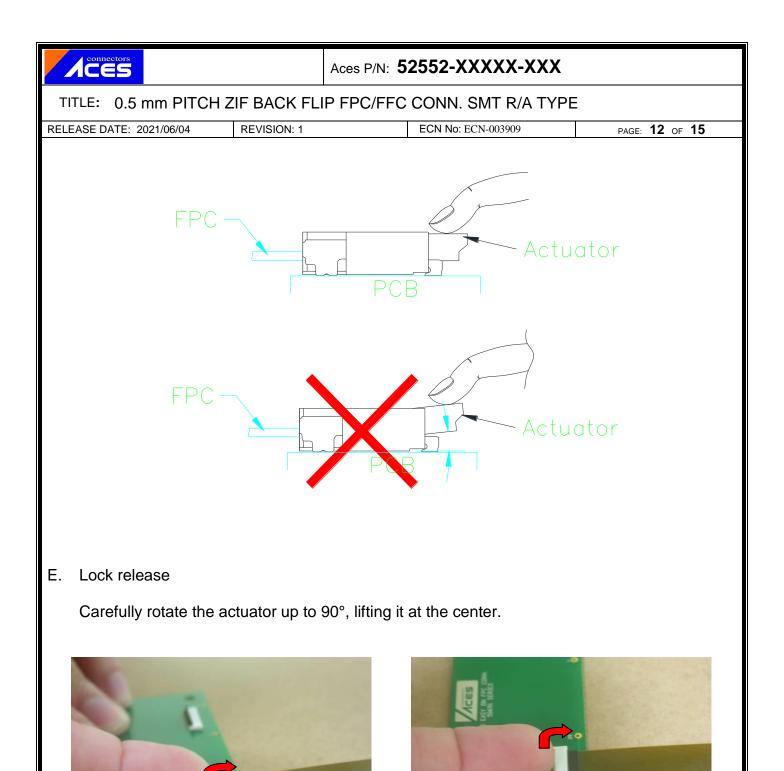


D. Locking

After FPC/FFC insertion, rotate the actuator down to a full stop, pushing it at the center.



About the lock operation When you lock, it is recommended what the actuator does as a whole, and the actuator was shut surely.



Rotate (lift)

.0

Do not open (lift) at one end.

